

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier	User Part Number					
Nexperia B.V.	BCP56-10H					
Name of Laboratory	Part Description					
Assembly reliability labs	Nexperia DHAM Small Signal Bipolar Transistor SMD package					
Based on AEC-Q101 Test	Test Conditions	Duration	# Lots	# Quantity	# Rejects	
# E1	TEST Pre- and Post-Stress Electrical Test Tamb = 25 °C	N/A	see below	all parts	see below	
# A1	PC Preconditioning JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	849	61170	0	
# B1	HTRB High Temperature Reverse Bias MIL-STD-750-1 M1039 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	202	16160	0	
# A4	TC Temperature Cycling JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	171	13680	0	
# A3 alt	AC Autoclave JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	173	13840	0	
# A2 alt	H3TRB High Humidity High Temperature Reverse Bias JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage ^[1]	1000 hours	173	13840	0	
# A5	IOL Intermittent Operating Life MIL-STD-750 Method 1037 ton = toff, devices powered to insure ΔTj = 100 °C for 15000 cycles	1000 hours	197	15760	0	
# C8	RSH Resistance to Solder Heat JESD22-A111 260 °C ± 5 °C	10 s	135	4050	0	
# C10	SD Solderability J-STD-002		342	3420	0	

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1)

Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Small Signal Bipolar Transistor	16160	0	0.26	3.81E+09

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